

ABSTRACT

An adhesive film according to the present disclosure includes a strip-shaped carrier film having a width of 100 mm or less, and a plurality of adhesive pieces disposed on the carrier film to be arranged in a longitudinal direction of the carrier film, in which the adhesive piece has a shape with at least one of a projection and a recess formed on at least one side of a rectangle or a square. A semiconductor device according to the present disclosure includes a semiconductor chip, a substrate to which the semiconductor chip is electrically connected, and an adhesive piece disposed between the semiconductor chip and substrate and bonding the semiconductor chip and the substrate, in which a shape of the semiconductor chip is different from a shape of the adhesive piece.